Preface of the 2014 IAENG International Conference on Electrical Engineering Special Session: Design, Analysis and Tools for Integrated Circuits and Systems

The International Workshop DATICS-IMECS'14: Design, Analysis and Tools for Integrated Circuits and Systems in the International MultiConference of Engineers and Computer Scientists 2014 will take place in Hong Kong, 12-14 March, 2014.

DATICS Workshops were initially created by a network of researchers and engineers both from academia and industry in the areas of Design, Analysis and Tools for Integrated Circuits and Systems. Recently, DATICS has been extended to the fields of Communication, Computer Science, Software Engineering and Information Technology.

The main target of DATICS-IMECS'14 is to bring together software/hardware engineering researchers, computer scientists, practitioners and people from industry to exchange theories, ideas, techniques and experiences related to all aspects of DATICS.

The International Program Committee (IPC) of DATICS-IMECS'14 consists of about 150 experts in the related fields of DATICS-IMECS'14 both from academia and industry. DATICS-IMECS'14 is partnered with CEOL: Centre for Efficiency-Oriented Languages (Ireland), Minteos (Italy), KATRI (Japan & Hong Kong), Distributed Thought (UK), Theory of Computation Lab - Yonsei University (South Korea), Baltic Institute of Advanced Technology - BPTI (Lithuania), Solari (Hong Kong), Transcend Epoch (Hong Kong) and Xi'an Jiaotong-Liverpool University - XJTLU (China - UK).

The DATICS-IMECS'14 Technical Program includes 15 papers which are organized into lecture sessions. As a result of the strong cooperation between the University of Hong Kong's Department of Electrical and Electronic Engineering and Xi'an Jiaotong-Liverpool University's Department of Computer Science and Software Engineering, we are pleased to announce the establishment of a student paper session at this year's DATICS-IMECS'14 Workshop. One of the main purposes of the student session is foster active participation of students and to create an environment where they can present the current results of their projects, which are attempts to address the pressing needs of our global social community. We hope that the session can provide students with ample opportunities to gain experience in presenting the results of their projects and in sharing their ideas with fellow students and colleagues through formal and informal discussions. The DATICS-IMECS'14 student session will not be possible without the invaluable assistance of Dr. Chi-Un Lei from the University of Hong Kong; and Professors Sheng-Uei Guan and Yong Yue, both of whom are from Xi'an Jiaotong-Liverpool University for their support and help. We would like to give our appreciation to them.

On behalf of the IPC, we would like to welcome the delegates and their guests to the DATICS-IMECS'14. We hope that you will enjoy the workshop and find the DATICS-IMECS'14 Technical Program exciting.

Ka Lok Man and Nan Zhang, DATICS-IMECS'14 IPC Chairs

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